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SEMICONDUCTOR DEVICE

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[There are no amendments to this patent.]

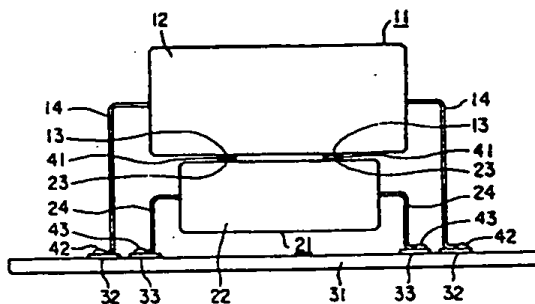
Abstract

Objective

To make it possible to realize a favorable-efficiency packing with a smaller packing area in a semiconductor device packed in a superposed manner on a printed-wiring substrate.

Constitution

For example, two semiconductor devices 1 and 2 are vertically superposed. Electrodes 11 and 21 of the opposite surfaces are electrically connected. In a state in which two electrodes 13 and 23 are connected, outer leads 14 and 24 of each semiconductor device 11 and 21 are connected with footprints 32 and 33 on a printed-wiring substrate 31. Two semiconductor devices 11 and 21 are then packed in a superposed manner, and signal lines, which can be made common, are replaced with the electrodes 13 and 23, so that the number of outer leads 14 and 24 are reduced, thereby realizing a miniaturized constitution.



Claim

A semiconductor device characterized by the fact that in a semiconductor device packed in a superposed manner on a packing substrate, electrodes mutually connected to the surface opposite to another semiconductor device are installed.

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